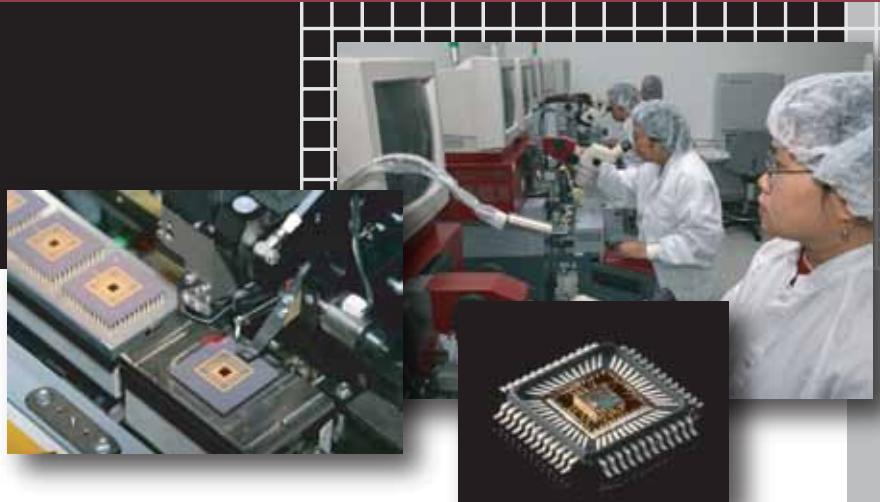


PROTOTYPE ASSEMBLY SERVICES



Capabilities:

- Wafer Dicing & Backgrinding
- Numerous Die Attach Options
- Wire Bonding with 0.8 to 3.0mil Gold Wire
- Extensive Encapsulation Options
- Remolding & Branding
- Same Day Turn-around Available
- Ideal for Rapid Prototype Assembly, Design Verification and Customer Samples

Quik-Pak delivers completely assembled prototype devices in as little as one day – enabling faster design verification and quicker time to market for your new products.

Whether you need die assembled in our proprietary Open Cavity Plastic or ceramic packages, multi-chip modules, chip-on-board or surface mount boards, we utilize state-of-the-art assembly equipment and processes to meet your needs. Our capabilities include:

Wafer Dicing & Backgrinding – Dicing of wafers up to 300mm in diameter and backgrinding down to 7 mils.

Die Attach – Using standard conductive or non-conductive epoxy or your qualified die attach material.

Wire Bond – Automatic bonding equipment can accommodate wire diameters from 0.8 to 3.0 mils, and bond pad pitch down to 40 microns.

Encapsulation Options – Quick-Pak offers a vast array of choices to meet your testing needs, ranging from open cavity to full encapsulation.

Remolding – Prototypes meet JEDEC standards for test socket and auto handling compatibility.

Branding – Pad-print a logo, part number and/or date code for clear identification.

Quik-Pak

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San Diego, CA 92127

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DELPHON

When you need to meet a project or customer deadline, you can count on Quik-Pak's reliable on-time delivery options for assembly – from standard three-day turnaround to one-day or even same-day expedited service.

Make Quik-Pak's high-quality prototype assembly service a standard part of your product development and verification process.